

CHEMTRONICS®

Technical Data Sheet

TDS # SWPbFree

Soder-Wick® Lead-Free SD Desoldering Braid

PRODUCT DESCRIPTION

Soder-Wick® Lead-Free is the state of the art in desoldering technology. It is specially designed for removal of today's high temperature lead-free solders. The single layer weave used for Soder-Wick® Lead-Free braid is lighter in mass than any other desoldering braid available and allows for lead-free solder removal at lower temperatures. Soder-Wick® Lead-Free responds faster than any other conventional desoldering braid. This unique design minimizes overheating and requires less "contact" time thus preventing heat damage to the PCB and sensitive components. For Lead-Free rework, Soder-Wick® has the answer.

- Fastest wicking and heat transfer
- High capacity for solder uptake
- Halide free, no corrosive residues
- Minimizes risk of heat damage to pads, components and PBCs
- Can be used with Tin/Lead solders
- RoHS compliant

TYPICAL APPLICATIONS

Soder-Wick® Lead-Free desoldering braid safely removes solder from:

- Thru-hole Components
- SMT Pads and BGA Pads
- Micro Circuits
- Terminals, Lugs and Posts
- Identification Script

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Flux Type	High-Temperature No Clean Type ROL0		
Specifications:	ANSI/IPC J STD-004 MIL-F-14256 F		
No Clean Flux Spec:	MIL-STD-883B Bellcore TR-NWT-000078 ANSI/IPC J SF818		
Shelflife:	2 years		
RoHS/WEEE Status			
Size #	Width Inches	Color	Width Metric
2	.060"	Yellow	1.5 mm
3	.080"	Green	2.0 mm
4	.110"	Blue	2.8 mm

STATIC DISSIPATIVE PACKAGING

Soder-Wick® Lead-Free is packaged on Static Dissipative bobbins to minimize the risk of damage associated with static electricity. The static dissipative bobbins qualify as electrostatic discharge protective per MIL-STD-1686C and MIL-HDBK-263B and meet the static delay rate provision of MIL-B-81705C.

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